



The QFN Lid Series was designed for Barry's C-QFN Air Cavity Family. There are several methods of attachment. Below are some of the more common methods.

**QFN Lid Attachment Options:**

**Epoxy:**

Ceramic lid is attached to the top surface of the package wall using B-stage non-conductive epoxy. We recommend our unmetallized lid configuration for this method (LID-XX-000).

This method does not result in a hermetic seal.

The leak rate of a properly sealed QFN package will be  $<1 \times 10^{-8}$  atm cc/s He. We provide QFN packages and lids separately in an open configuration. Therefore we test in accordance with MIL-STD-883 method 1014 Test Condition A4 as appropriate for unlidded packages.

† The temperature required to melt even this type of glass may present problems depending on the characteristics of the semiconductor used and the attachment method.

**Sealing Glass†:**

Ceramic lid is attached to the top surface of the package wall using a low temperature glass.

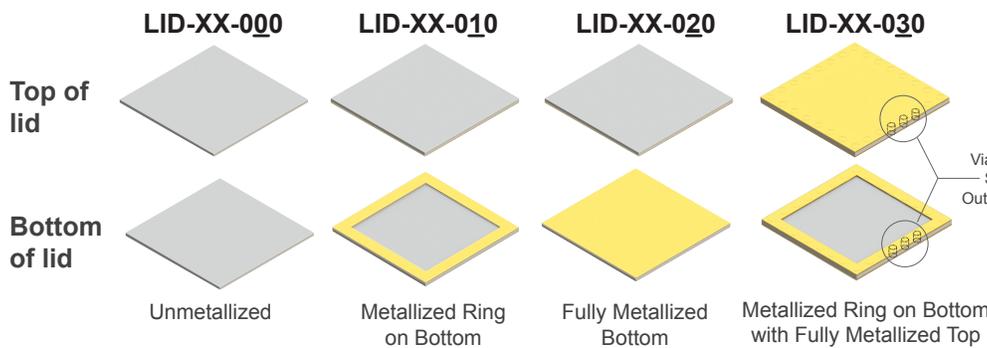
This method results in a hermetic seal.

**Solder:**

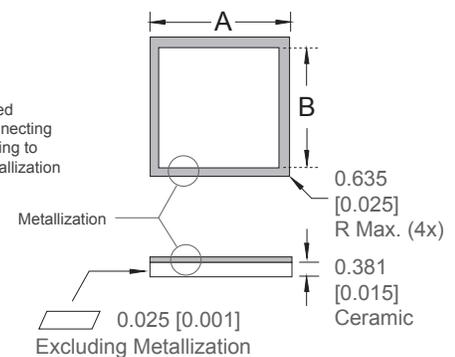
Metallized ceramic lid or metal lid is attached to the metallized top surface of the package wall. The most common alloy used is AuSn eutectic.

This method results in a hermetic seal.

**QFN Lid Configurations:**



**QFN Lid Dimensions:**



**Metallization:** RoHS 50μ inches gold (min.) over 50μ inches nickel (min.) over tungsten or MoMN refractory metallization.

**QFN Lid Ordering Information:**

**Example Part Number: LID-44-030**

LID - ## - 0#0 - X

Ceramic QFN Lid Prefix:

Lid Size:

A

B

Lid Configuration:

33 - Fits 3mm C-QFN	3.0 [0.118]	1.905 [0.075]
44 - Fits 4mm C-QFN	4.0 [0.157]	2.845 [0.112]
55 - Fits 5mm C-QFN	5.0 [0.197]	3.835 [0.151]
66 - Fits 6mm C-QFN	6.0 [0.236]	4.826 [0.190]
77 - Fits 7mm C-QFN	7.0 [0.276]	5.842 [0.230]
88 - Fits 8mm C-QFN	8.0 [0.315]	6.833 [0.269]
99 - Fits 9mm C-QFN	9.0 [0.354]	7.848 [0.309]

- 000 - Unmetallized
- 010 - Metallized Ring on Bottom
- 020 - Fully Metallized Bottom
- 030 - Metallized Ring on Bottom with Fully Metallized Top

Attachment Preforms (optional, otherwise leave blank):

- B - Non-Conductive Epoxy
- C - Conductive Epoxy
- G - Sealing Glass

80/20 AuSn Solder Preforms are available and are **sold separately**.

Request part number 19282-##-020 where ## denotes lid size. The 19282-XX-020 80/20 AuSn data sheet is available on our website!

(i.e. 19282-33-020: 3mm 80/20 AuSn lid preform)

Dimensions in mm [inches]. Tolerance is ±0.127 [0.005] unless otherwise stated

Barry Industries reserves the right to change part number and/or process without notification.

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